



67,200-506

Serial Number 09/920,911

2812
#4/Response
11-22-02
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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

TO: ASSISTANT COMMISSIONER FOR PATENTS
Washington, D.C. 20231

FROM: Tung & Associates
838 West Long Lake Road - Suite 120
Bloomfield Hills, MI 48302

DATE: 24 October 2002

REF: Applicant : Yu et al. Filing Date : 2 August 2001
Serial No : 09/920,911 Att'y No. : 67,200-506
Art Unit : 2812 Examiner : Richard A. Booth
Title : Thermal Compensation Method for Forming Semiconductor
Integrated Circuit Microelectronic Fabrication

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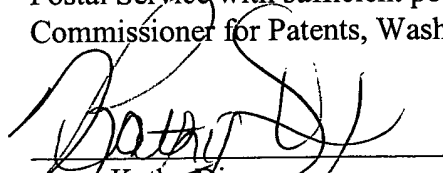
RESPONSE TO OFFICE ACTION

Sir:

In response to an office action mailed on 24 September 2002, please consider the following remarks pertaining to the above referenced application.

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail in an envelope addressed to the Assistant Commissioner for Patents, Washington D.C., 20231 on 11/1 2002


Kathy Dixon

11/1/02
Date